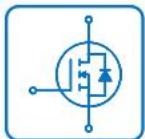




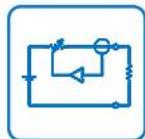
ESD



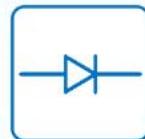
TVS



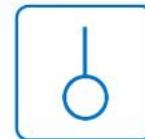
MOS



LDO



Diode



Sensor



DC-DC

Product Specification

▶ Domestic Part Number	IRF7501
▶ Overseas Part Number	IRF7501
▶ Equivalent Part Number	IRF7501



20V N+N-Channel Enhancement Mode MOSFE

Description

The IRF7501 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

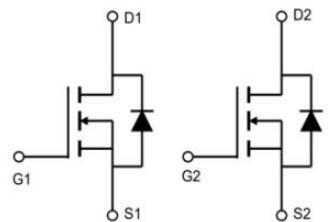
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

$V_{DS} = 20V$ $I_D = 5.0A$

$R_{DS(ON)} < 28m\Omega$ @ $V_{GS}=4.5V$

$R_{DS(ON)} < 38m\Omega$ @ $V_{GS}=2.5V$

Dual SOP8 Pin Configuration**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, V_{GS} @ 4.5V ¹	5.0	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, V_{GS} @ 4.5V ¹	3.3	A
I_{DM}	Pulsed Drain Current ²	25	A
$P_D@T_A=25^\circ C$	Total Power Dissipation ³	1.65	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	78	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	--	-	°C/W

20V N+N-Channel Enhancement Mode MOSFE

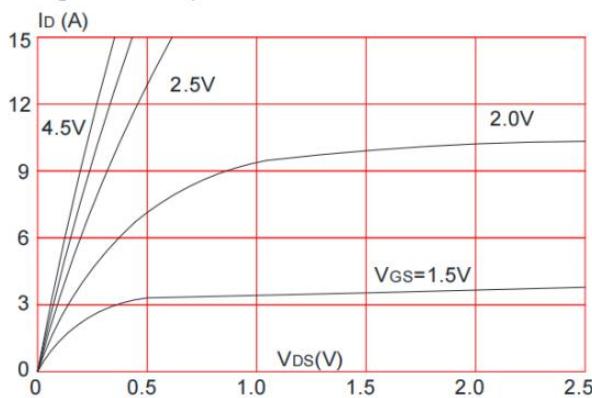
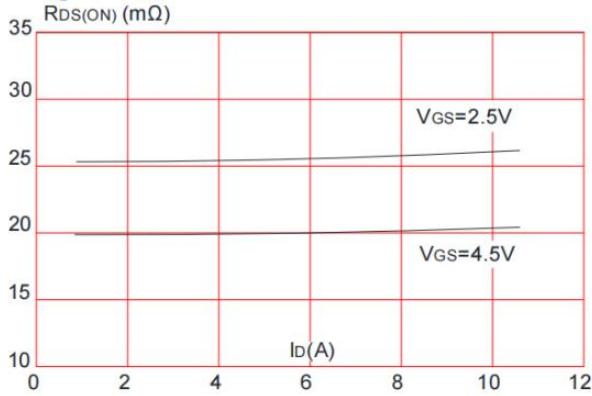
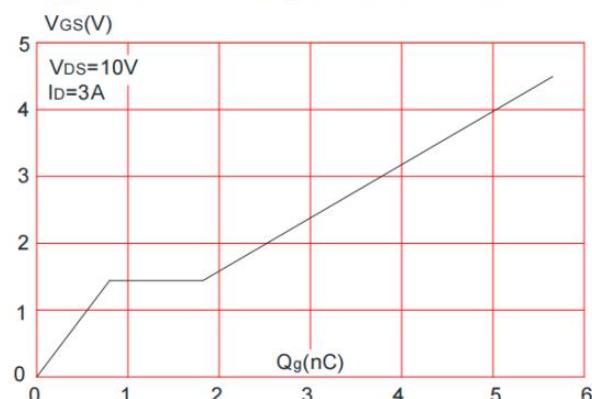
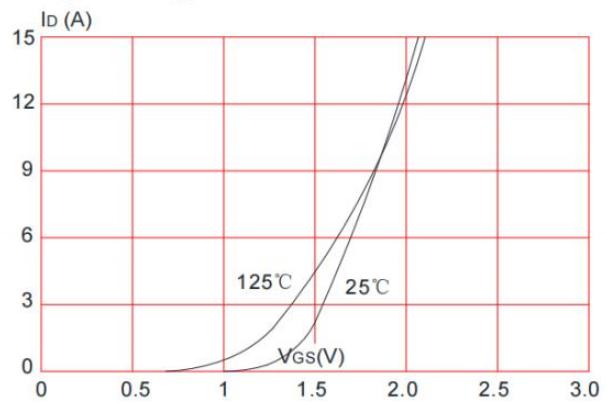
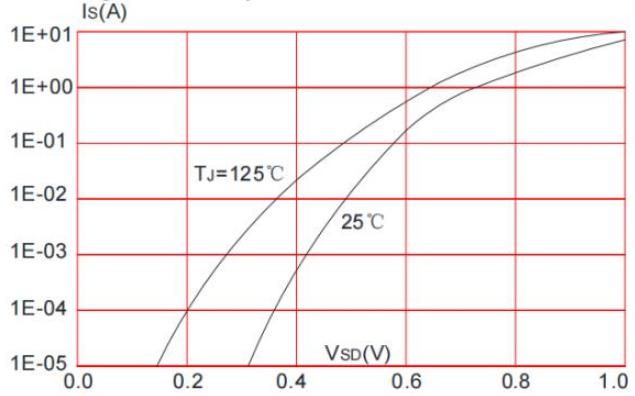
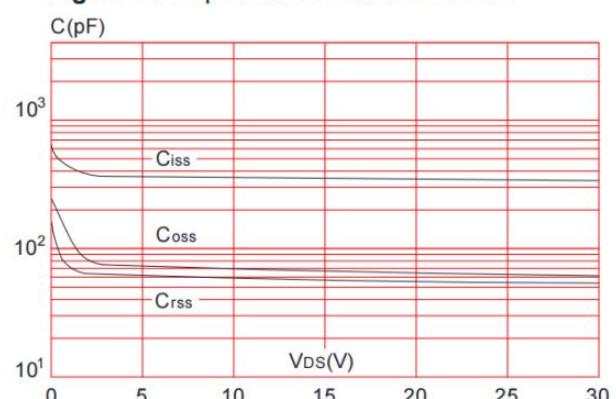
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V},$	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.4	0.7	1.0	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=4.5\text{V}, I_D=6\text{A}$	-	20	28	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=5\text{A}$	-	25.5	38	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	358	-	pF
C_{oss}	Output Capacitance		-	69.3	-	pF
C_{rss}	Reverse Transfer Capacitance		-	58.5	-	pF
Q_g	Total Gate Charge	$V_{DS}=10\text{V}, I_D=3\text{A}, V_{GS}=4.5\text{V}$	-	5.6	-	nC
Q_{gs}	Gate-Source Charge		-	0.8	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10\text{V}, I_D=6\text{A}, R_{\text{GEN}}=3\Omega, V_{GS}=4.5\text{V}$	-	16	-	ns
t_r	Turn-on Rise Time		-	51	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	21	-	ns
t_f	Turn-off Fall Time		-	19	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	6	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	24	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=6\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

20V N+N-Channel Enhancement Mode MOSFET

Typical Performance Characteristics**Figure 1:** Output Characteristics**Figure 3:** On-resistance vs. Drain Current**Figure 5:** Gate Charge Characteristics**Figure 2:** Typical Transfer Characteristics**Figure 4:** Body Diode Characteristics**Figure 6:** Capacitance Characteristics

20V N+N-Channel Enhancement Mode MOSFE

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

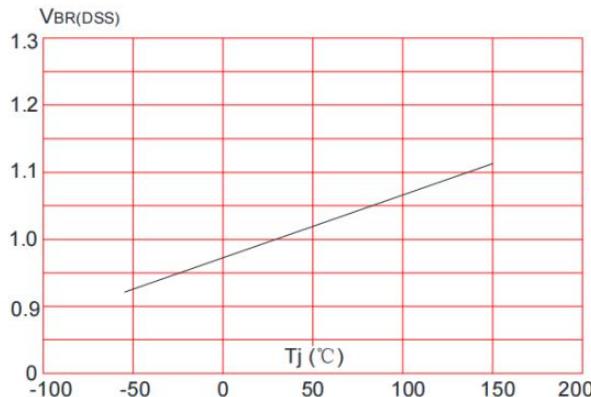


Figure 8: Normalized on Resistance vs. Junction Temperature

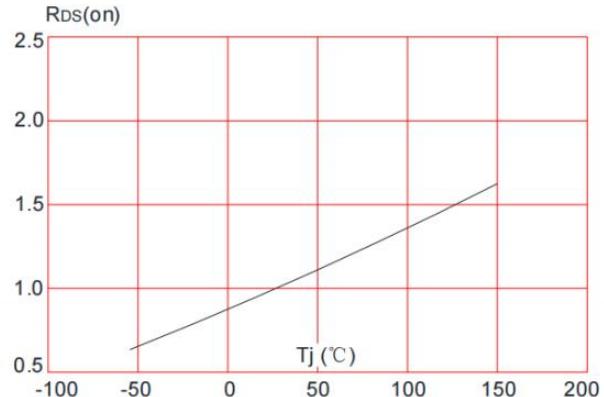


Figure 9: Maximum Safe Operating Area

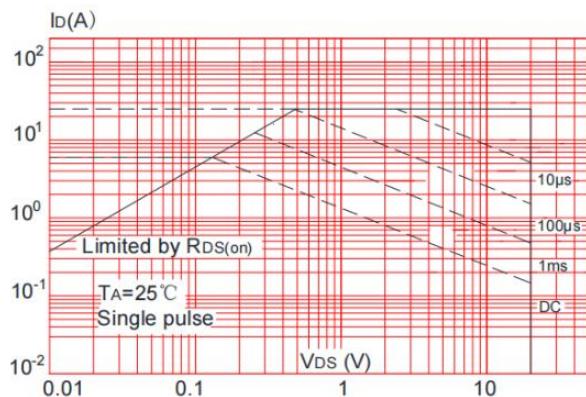


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

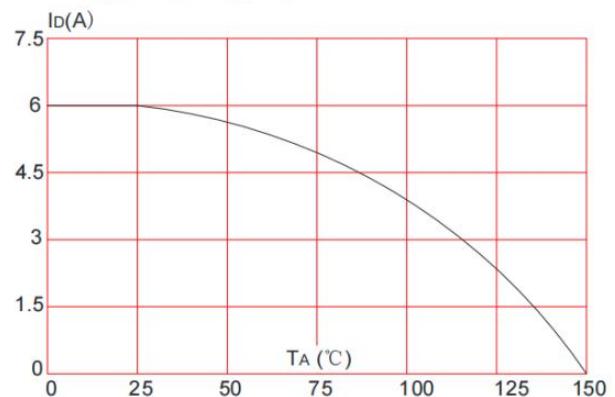
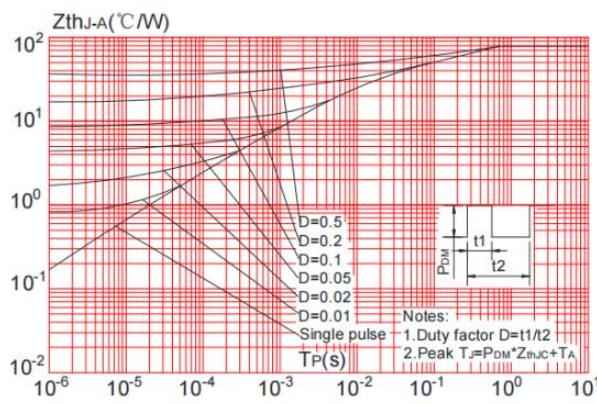
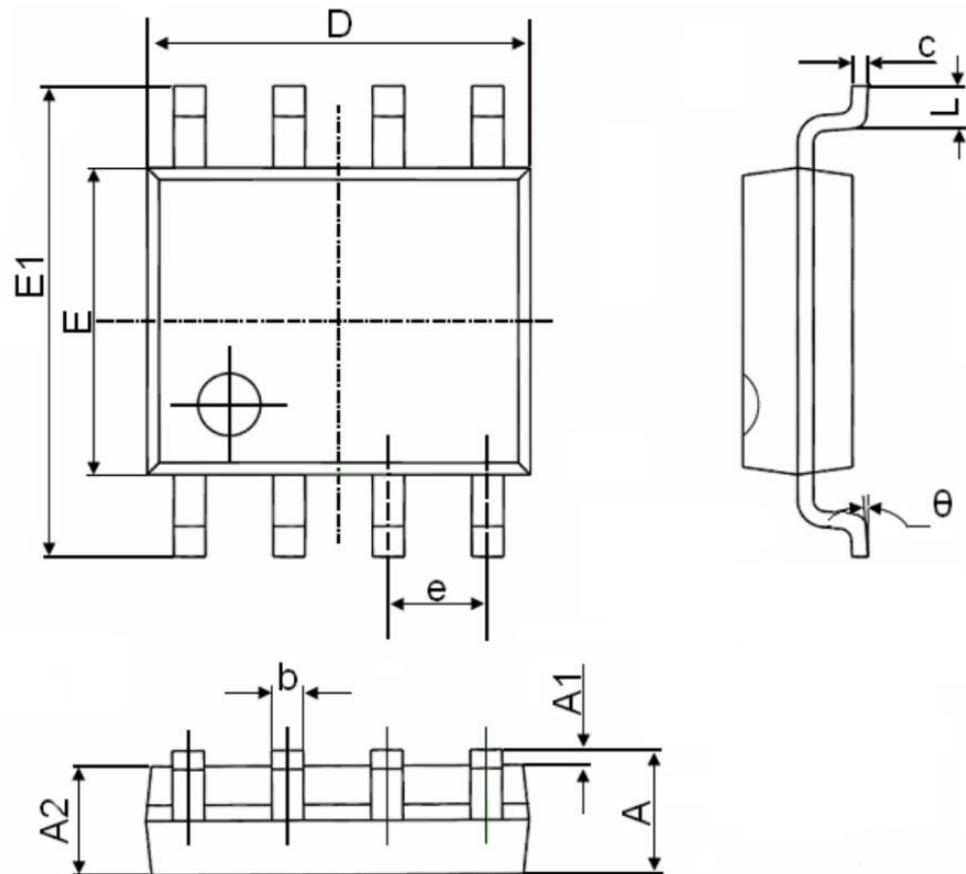


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



20V N+N-Channel Enhancement Mode MOSFE

Package Mechanical Data-SOP-8


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Disclaimer

EVVOSEMI ("EVVO") reserves the right to make corrections, enhancements, improvements, and other changes to its products and services at any time, and to discontinue any product or service without notice.

EVVO warrants the performance of its hardware products to the specifications applicable at the time of sale in accordance with its standard warranty. Testing and other quality control techniques are used as deemed necessary by EVVO to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

Customers should obtain and confirm the latest product information and specifications before final design, purchase, or use. EVVO makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does EVVO assume any liability for application assistance or customer product design. EVVO does not warrant or accept any liability for products that are purchased or used for any unintended or unauthorized application.

EVVO products are not authorized for use as critical components in life support devices or systems without the express written approval of EVVOSEMI.

The EVVO logo and EVVOSEMI are trademarks of EVVOSEMI or its subsidiaries in relevant jurisdictions. EVVO reserves the right to make changes without further notice to any products herein.